



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

OOHASHI, Takeshi et al.

Group Art Unit: 1711

Serial No.: 09/926,033

Examiner: Not Yet Assigned

Filed: November 7, 2001

P.T.O. Confirmation No.: 3978

For. PHOTSENSITIVE RESIN COMPOSITION, PHOTSENSITIVE ELEMENT
USING THE SAME, PROCESS FOR PRODUCING RESIST PATTERN AND
PROCESS FOR PRODUCING PRINTED WIRING BOARD

THIRD PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Date: March 4, 2003

Sir:

Prior to examination of the above-identified application, please note the following
amendments thereto:

IN THE SPECIFICATION:

Please amend the specification as follows:

(Page 30, Table 3):

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TC 1700 MAIL ROOM

TABLE 3

Materials		Example No.				Comparative Example No.			
		1	2	3	4	1	2	3	4
(A)	a	60	60	-	-	60	60	60	-
	b	-	-	60	60	-	-	-	60
(C)	Nonylphenoxy- octa(ethylenoxy) acrylate	10	10	10	10	-	-	-	-
	Nonylphenoxyethylenoxy acrylate	-	-	-	-	10	-	-	-
	EO, PO-modified urethane dimethacrylate ¹	10	-	10	-	10	10	10	10
	β -hydroxypropyl- β' - methacryloyloxyethyl o-phthalate	-	-	-	-	-	-	30	-
	2,2-bis[4-(methacryloxy-penta- ethoxy)phenyl]propane	20	30	20	30	20	20	30	30

¹: A compound of the general formula (IV) wherein R⁷ and R⁸ each are a methyl group, X¹
and X² each are an ethylenoxy group, Y¹ and Y² each are an isopropyleneoxy group, Z³ is
a hexylene group, p and q each are 1, and r and v each are 9.